

# Two part thermal gel pad XK-S30

## Features:

- 1:1 mix
- (no cure by-product)
- Low stress applications
- Easy to use
- Fast cure by heating



## Applications

- Automotive electronics
- Telecommunications
- Computer&peripherals
- Thermally conductive & vibration dampening
- Between any heat-generating semiconductor and a heat sink

	XK-S30	METHOD	UNIT
Color / Part A	White	Visual	
Color / Part B	Yellow	Visual	
Features	Soft gel	-	-
Density	3.0	ASTM D792	g/cm3

### Before Cured Property

A:B	1:1	-	-
Mixed Viscosity (20rpm)	350	ASTM D2196	Pa.s
Shelf Life @ 25°C	6		month

### After Cured Property

Color	Yellow	Visual	-
Cure Schedule 1	6 hr/25°C		
Cure Schedule 2	40 min/80°C		
Cure Schedule 3	10 min/125°C		
Working time	120min/25°C		
Hardness	60	ASTM D2240	Shore 00
	30	JIS K7312	AskerC
Tensile Strength.	0.2	ASTM D412	Mpa
Elongation	>50	ASTM D412	%
Continuous Use Temp	-60~150		°C

### Electrical Property

Dielectric strength	>10	ASTM D149	KV/mm
Volume resistivity	>10 <sup>12</sup>	ASTM D257	Ohm-cm
Dielectric Constant	5	ASTM D150	(1KHz)
Flame Rating	V-0	UL94	

### Thermal Property

Thermal Conductivity	3.0	ASTM D5470	W/m*K
Heat Capacity	1	ASTM E1269	J/g-K